



32nd IEEE European Test Symposium

24th - 28th May 2027 | London, UK

www.ets2027.co.uk

General Chairs

Lee Harrison, Siemens EDA, Great Britain
Gareth Taylor, Brunel University, Great Britain

Program Chair

Leticia Maria Bolzani Pöhls, IHP, Germany

Topic Chairs

T1 – Haralampos Stratigopoulos, Sorbonne University, France
T1 – Maria Michael, University of Cyprus, Cyprus
T2 – Daniel Tille, Siemens EDA, Germany
T2 – Riccardo Cantoro, Politecnico di Torino, Italy
T3 – Ioana Vatajelu, University Grenoble Alpes, TIMA, France
T3 – Moritz Fieback, TU Delft, Netherlands
T4 – Motta Taouil, TU Delft, Netherlands
T4 – Ilia Polian, University of Stuttgart, Germany
T5 – Florence Azais, University of Montpellier, France
T5 – Gildas Leger, IMSE-CNM-CSIC, Spain
T6 – Erik Larsson, University of Lund, Sweden
T6 – Artur Jutman, Testonica, Estonia
T7 – Graziano Pravadelli, University of Verona, Italy
T7 – Jaan Raik, TalTech, Estonia
T8 – Matteo Sonza Reorda, Politecnico di Torino, Italy
T8 – Arnaud Virazel, University of Montpellier, LIRMM, France

Finance Chairs

Gareth Taylor, Brunel University, Great Britain
Ruiheng Wu, Brunel University, Great Britain

Special Session Chairs

Sebastian Huhn, Siemens EDA, Germany
Angeliki Kritikakou, INRIA, France

Panel Chairs

Alberto Bosio, Ecole Centrale de Lyon, France
Anthony Coyette, Onsemi, Belgium

Embedded Tutorial Chairs

Stefano di Carlo, Politecnico di Torino, Italy
Anteneh Gebregiorgis, TU Delft, Netherlands

Industrial Board Chairs

David Appello, Technoprobe, Italy
Rene Krenz-Baath, TH Wildau, Germany

Industrial Relations Chairs

Paolo Bernardi, Politecnico di Torino, Italy
Stephen Eggersgluess, Siemens EDA, Germany

Student Activities Coordinator

Maksim Jenihhin, TalTech, Estonia
Marcello Traiola, INRIA, France

TTTC's E.J. McCluskey Best Doctoral Chairs

Liviu Miclea, Technical University of Cluj-Napoca, Romania
Annachiara Ruospo, Politecnico di Torino, Italy

PhD Forum Chairs

Paolo Rech, Trento University, Italy
Emanuele Valea, CEA-List, France

Publication Chairs

Balajiraja Ravinarayanan, Siemens EDA, Ireland

Publicity Chairs

Sil Singh, Siemens EDA
Alexandra Kourfali, EuroHPC JU, Belgium

Award Chairs

Zebo Peng, Linköping University, Sweden
Lorena Anghel, Grenoble INP/PHELMIA, France

ETS Workshop Chairs

Anshuman Chandra, Siemens, USA
James Pickford, Swansea University, Great Britain

Late Breaking News Chairs

Ernesto Sanchez, Politecnico di Torino, Italy
Mohammed Hasan Ahmadi Ivan, TalTech, Estonia

Web Chair

Ioana Pisica, Brunel University, Great Britain

PRELIMINARY CALL FOR PAPERS

The European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, hot topics and new trends, as well as industrial case-studies and applications in the area of electronic-based circuits and systems testing, reliability, safety, security and validation. ETS27 will take place at London, UK, and it is organized by the Brunel University of London. In addition to regular Scientific Papers, Keynotes, Special Sessions, Panels, and Embedded Tutorials, ETS'27 also features papers/highlights/demos and vendor sessions from the industry, as well as a rich set of student-related activities including a PhD Forum and the TTTC's E.J. McCluskey Best Doctoral Thesis Award Contest. ETS is the major event of the European Test Week that also includes a Test Spring School (TSS) and Fringe Workshops.

The areas of interest include (but are not limited to) the following topics:

- T1 – Dependable AI and AI for Testing
- T2 – Functional Safety, Fault Tolerance and Reliability
- T3 – Methods for Emerging Technologies and Architectures
- T4 – Security and Trust
- T5 – Test and Reliability for Analog, Mixed-Signal, and RF
- T6 – DFT, Test Access Standards and Test application
- T7 – Validation, Verification, and Debug
- T8 – Test Generation, Fault Modelling & Simulation, Diagnosis

Submissions | ETS 27 seeks:

Scientific Papers presenting novel unpublished and complete research works (up to 6 pages) to be peer-reviewed and possibly accepted either as a full 6-page paper accompanied with an oral presentation or a short 4-page paper accompanied with a poster presentation. ETS'27 fully complies with the most common publication policies regarding multiple submissions, plagiarism, etc. Papers are evaluated according to relevance to the symposium, technical merit, level of innovation, paper organization and language.

Industrial Contributions for the Informal Proceedings, presenting results, highlights, or demos from the industry (up to 6 pages); at least one author from the industry is required.

Student Contributions, such as PhD Forum, which targets PhD students who have preliminary research results, and the TTTC's E.J. McCluskey Best Doctoral Thesis Award Contest, offering an ample stage to present PhD research and theses, and – being a regional semi-final – the chance to advance to the award's finals taking place during ITC 2027.

Late Breaking Results for high-quality submissions that present new findings, emerging ideas, or recent breakthroughs across all domains traditionally covered by ETS'27.

ETS27 also seeks proposals for:

Special Sessions, Panels, and Embedded Tutorials
Fringe Workshops, to be held on 27-28th May, 2027

Key Dates for Scientific Papers:

Abstract Deadline	8 th December 2026
Final pdf submission Deadline	15 th December 2026
Authors notification	19 th February 2026
Camera Ready	12 th March 2027
Author registration	26 th March 2027

For further information, please contact:

Lee Harrison General Co-Chair Siemens EDA, UK lee.harrison@siemens.com	Gareth Taylor General Co-Chair Brunel University of London info@ets2027.co.uk
--	---

Leticia Maria Bolzani Pöhls
Program Chair
IHP, Germany
poehls@ihp-microelectronics.com

SPONSORS

Financial Sponsors:



Corporate Support:

SIEMENS

Technical Sponsors:

